### 502798853 05/07/2014

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2845448

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
CHING-FU YEH	04/28/2014
MING-HAN LEE	04/29/2014

#### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.	
Street Address: NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK		
City: HSINCHU		
State/Country:	TAIWAN	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14271726

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Phone: 949 387 2885 Email: inbox@wpatca.com

Correspondent Name: WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS

Address Line 1: 1100 QUAIL STREET, SUITE 202

Address Line 4: NEWPORT BEACH, CALIFORNIA 92660

ATTORNEY DOCKET NUMBER:	18506-712
NAME OF SUBMITTER:	ANTHONY KING
SIGNATURE:	/Anthony King/
DATE SIGNED:	05/07/2014

**Total Attachments: 2** 

source=US3051-Assignment#page1.tif source=US3051-Assignment#page2.tif

PATENT 502798853 REEL: 032840 FRAME: 0083

## **ASSIGNMENT**

WHEREAS, I(we), <u>YEH, CHING-FU</u> and <u>LEE, MING-HAN</u>, whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

#### INTERCONNECT STRUCTURE AND MANUFACTURING METHOD THEREOF

(hereinafter referred to as the INVENTION) for which an applic	ation for United States Let	ters Patent /Utility Patent
is executed on even date herewith unless at least one of the fol		· ·
☐ United States Design Patent was	_	
□ executed on:		
☐ filed on: Serial No	). <b>:</b>	
☐ established by PCT International Patent Application N	No.: filed:	designating the
United States of America		, 5
☐ issued on as U.S. Patent No.:		
WHEREAS, TAIWAN SEMICONDUCTOR MANUFA	CTURING COMPAN	Y LTD. whose post office
address is NO.8, LI-HSIN RD. 6, HSINCHU SCIE	NCE PARK, HSINC	HU, TAIWAN, R.O.
hereinafter referred to as ASSIGNEE, is desirous of acquiring t	he entire right, title and in	terest in and to the same
the United States and its territorial possessions;		•

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

	Assignor Name YEH, CHING-FU	Address NO. 113, JINSHAN 7TH ST., EAST DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
V	Signature of Assignor (X) Yeh, Ming - Fy	Date of Signature (X) $_{\mathcal{V}}(\varphi, \varphi, \mathcal{V})$
	Name of Witness (optional)	Name of Witness (optional)
	Signature of Witness (optional)	Signature of Witness (Optional)

PATENT REEL: 032840 FRAME: 0084

Assignor Name LEE, MING-HAN	Address  4F., NO.63, LINSEN N. RD., ZHONGSHAN DIST., TAIPEI CITY 104, TAIWAN (R.O.C.)
Signature of Assignpr (X)  Y'- VAC Q	Date of Signature (X) 2014. 4. 19
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

- 2 -